



Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- External Creepage ≥ 7.5mm (S/SL Type)
- External Creepage ≥ 8.0mm (SLM Type)
- Operating temperature range 55 ℃ to 110 ℃
- Regulatory Approvals
 - UL UL1577 (E364000)
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - IEC60065, IEC60950

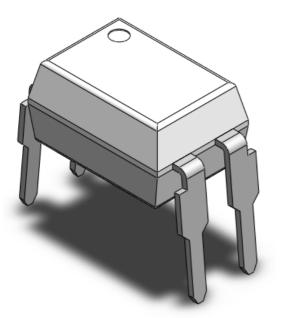
Description

The CT817 series consists of a photo transistor optically coupled to a gallium arsenide Infrared-emitting diode in a 4-lead DIP package different lead forming options.

Applications

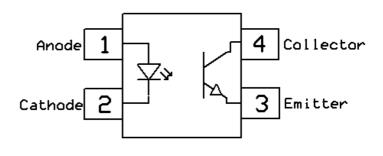
- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Package Outline



Note: Different lead forming options available. See package dimension.

Schematic





DC Input 4-Pin Phototransistor Optocoupler

Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage	5000	V _{RMS}	
Ртот	Total power dissipation	200	mW	
Topr	Operating temperature	-55 ~ +110	°C	
Тsтg	Storage temperature	-55 ~ +150	°C	
TsoL	Soldering temperature	260	°C	
Emitter		·		
l _F	Forward current	60	mA	
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)	1	А	
V _R	Reverse voltage	6	V	
PD	Emitter power dissipation	100	mW	
Detector		·		
PD	Detector power dissipation	150	mW	
Вусео	Collector-Emitter Breakdown Voltage	35	V	
Bveco	Emitter-Collector Breakdown Voltage	6	V	
Ic	Collector Current	50	mA	

DC Input 4-Pin Phototransistor Optocoupler

Electrical Characteristics $T_A = 25 \, ^{\circ}\text{C}$ (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA		1.24	1.4	V	
IR	Reverse Current	V _R = 6V	-	-	5	μΑ	
C _{IN}	Input Capacitance	f= 1MHz	-	10	30	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
Bvceo	Collector-Emitter Breakdown	I _C = 100μA	35	-	-	V	
Bveco	Emitter-Collector Breakdown	I _E = 100μA	6	-	-	V	
ICEO	Collector-Emitter Dark Current	V _{CE} = 20V, I _F =0mA	-	-	100	nA	

Transfer Characteristics

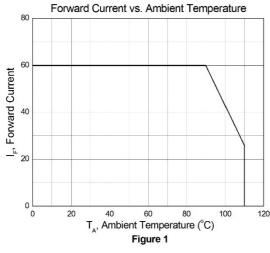
Symbol	Parameters		Test Conditions	Min	Тур	Max	Units	Notes
	Current Transfer Ratio CT8176	CT817	I _F = 5mA, V _{CE} = 5V	50	ı	600	%	
		CT817A		80	-	160		
CTR		CT817B		130	-	260		
		CT817C		200	-	400		
		CT817D		300	-	600		
Various	Collector-Emitter Satura		I _F = 20mA, I _C = 1mA		0.1	0.2	٧	
V _{CE(SAT)}	Voltage		IF= ZUIIIA, IC= IIIIA	-	0.1	0.2	V	
R _{IO}	Isolation Resistance		V _{IO} = 500V _{DC}	5x10 ¹⁰	-	-		
Сю	Isolation Capacitance		f= 1MHz	-	0.25	1	pF	

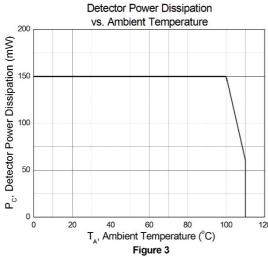
Switching Characteristics

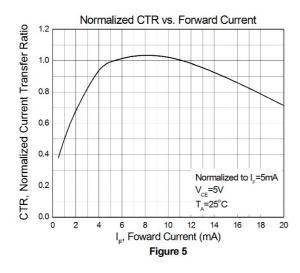
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
tr	Rise Time	I _C = 2mA, V _{CE} = 2V		6	18		
t _f	Fall Time	R _L = 100	-	8	18	μS	

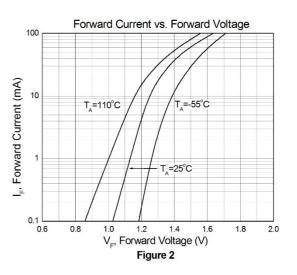


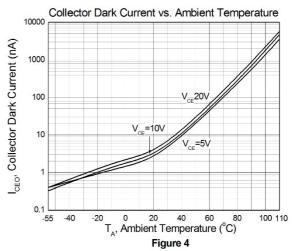
Typical Characteristic Curves

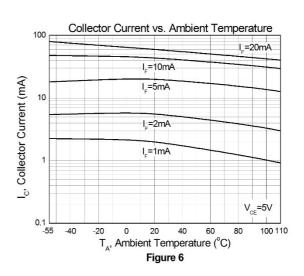






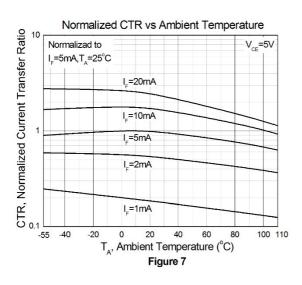


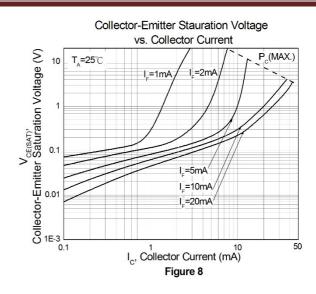


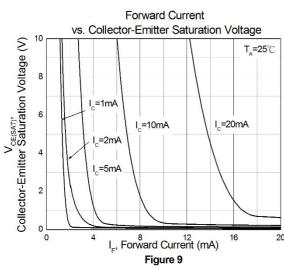


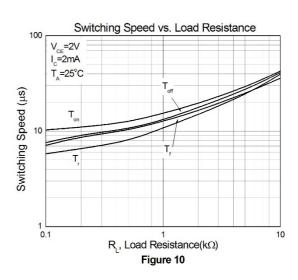


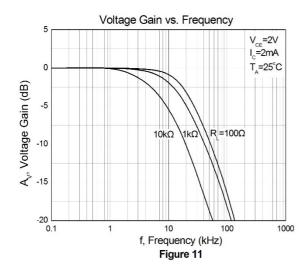
DC Input 4-Pin Phototransistor Optocoupler











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Test Circuit

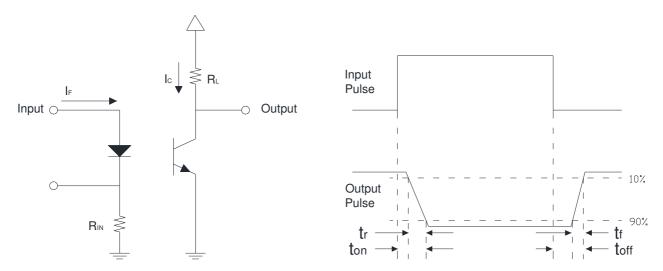
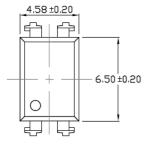


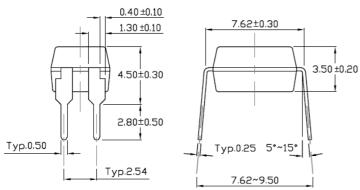
Figure 12: Switching Time Test Circuits



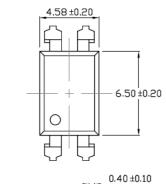
Package Dimension Dimensions in mm unless otherwise stated

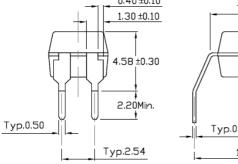
Standard DIP - Through Hole

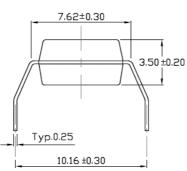




Gullwing (400mil) Lead Forming – Through Hole (M Type)



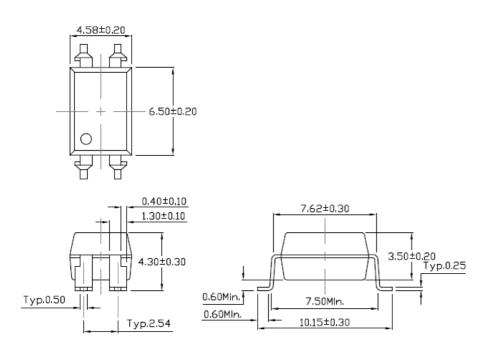




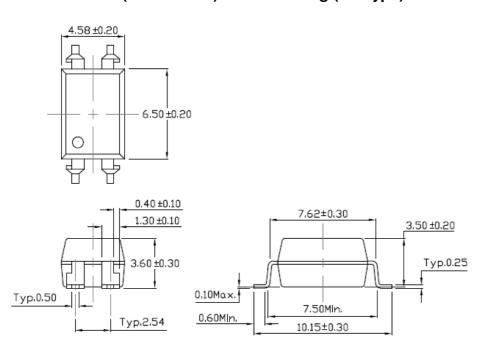




Surface Mount Lead Forming (S Type)



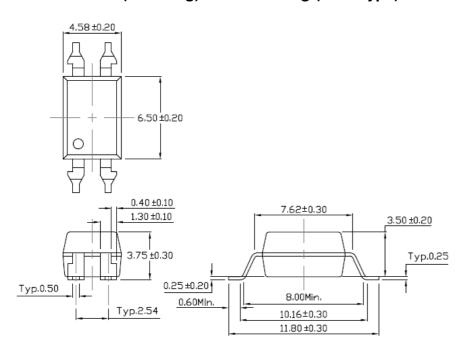
Surface Mount (Low Profile) Lead Forming (SL Type)







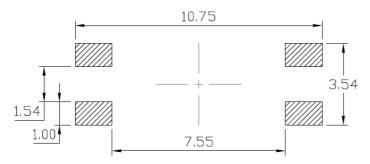
Surface Mount (Gullwing) Lead Forming (SLM Type)



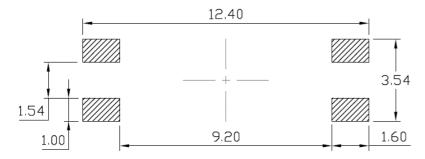


Recommended Solder Mask Dimensions in mm unless otherwise stated

Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming



Surface Mount (Gullwing) Lead Forming



Marking Information



Note:

CT : Denotes "CT Micro"

817 : Part NumberV : VDE OptionR : CTR RankY : Fiscal YearWW : Work Week

K : Manufacturing Code





Ordering Information

CT817X(V)(Y)(Z)-HG

X = Part No. (X=A, B, C, D or None)

V = VDE Option (V or None)

Y = Lead form option (S, SL, M, SLM or none)

Z = Tape and reel option (T1, T2, T3, T4 or none)

H = Lead frame option (H: Iron, None: Copper)

G= Material option (G: Green, None: Non-green)

Option	Description	Quantity
None	Standard 4 Pin Dip	100 Units/Tube
М	Gullwing (400mil) Lead Forming	100 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1500 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1500 Units/Reel
S(T3)	Surface Mount Lead Forming – With Option 3 Taping	1000 Units/Reel
S(T4)	Surface Mount Lead Forming – With Option 4 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1500 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1500 Units/Reel
SL(T3)	Surface Mount (Low Profile) Lead Forming- With Option 3 Taping	1000 Units/Reel
SL(T4)	Surface Mount (Low Profile) Lead Forming – With Option 4 Taping	1000 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming- With Option 1 Taping	1500 Units/Reel
SLM(T2)	Surface Mount (Gullwing) Lead Forming – With Option 2 Taping	1500 Units/Reel

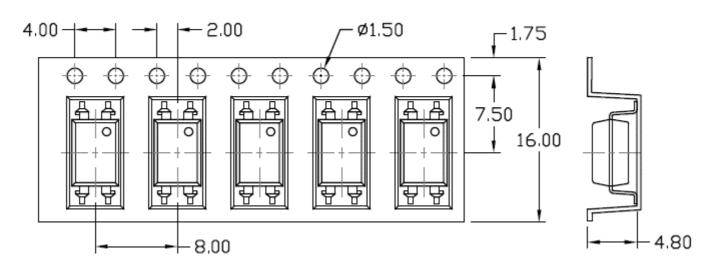




Carrier Tape Specifications Dimensions in mm unless otherwise stated

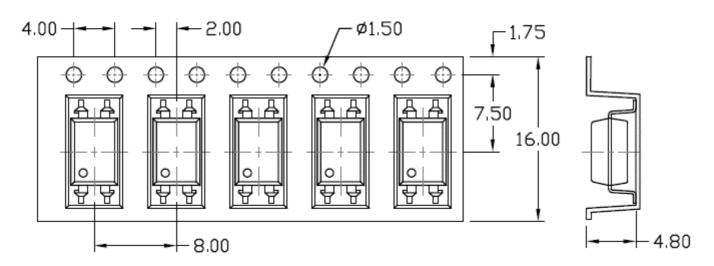
Option S(T1) & SL(T1)

Input Direction



Option S(T2) & SL(T2)

Input Direction

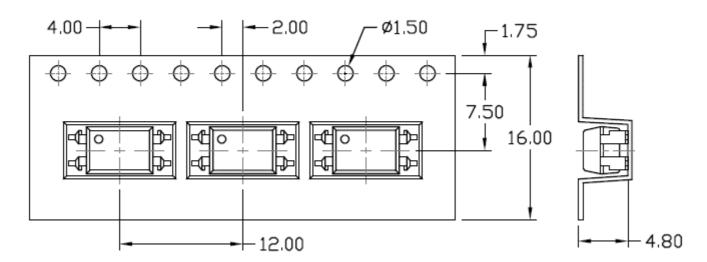






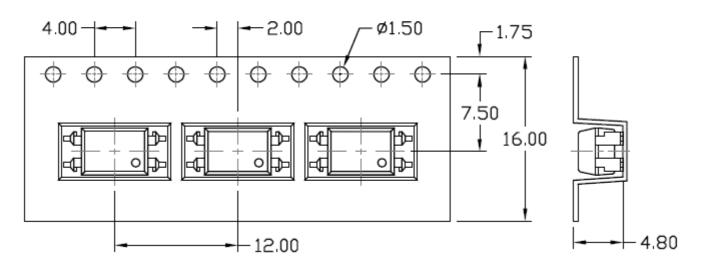
Option S(T3) & SL(T3)

Input Direction

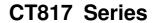


Option S(T4) & SL(T4)

Input Direction



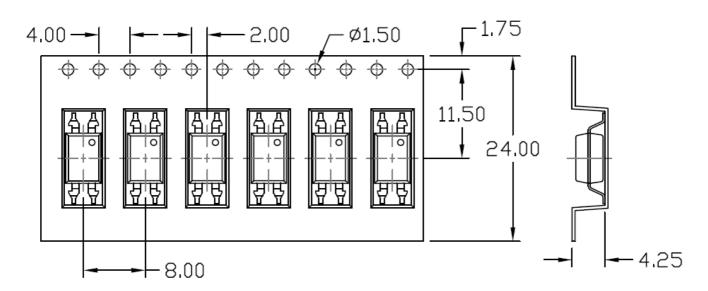
Rev 1 Dec, 2014





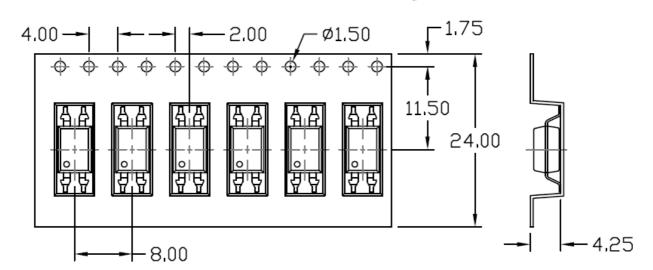
Option SLM(T1)

Input Direction



Option SLM(T2)

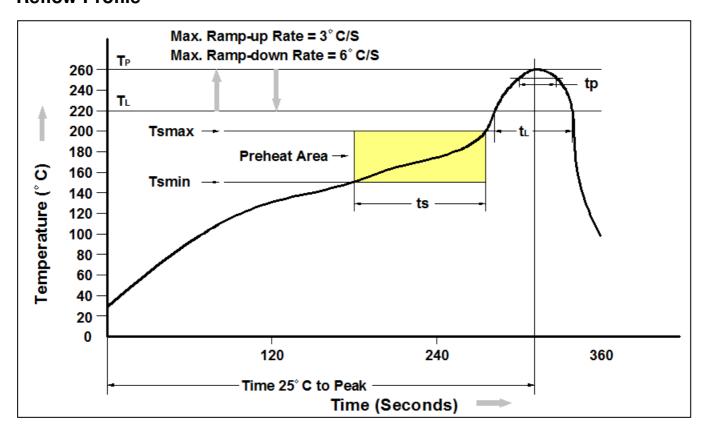
Input Direction







Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150℃
Temperature Max. (Tsmax)	200℃
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (TL)	217℃
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260℃ +0℃ / -5℃
Time (t _P) within 5 °C of 260 °C	30 seconds
Ramp-down Rate (T _P to T _L)	6 ℃/second max
Time 25 ℃ to Peak Temperature	8 minutes max.



DC Input 4-Pin Phototransistor Optocoupler

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TLP118(TPL,E) TLP2309(E(T TLP2366(TPL,E TLP521-2XGB TLP621-2XGB JANTXV4N24U 8102802PC 5962-8767902XA 59628876801XA 5962-8957101PA SFH6318T 6N135-300E TIL198 TLP104(TPR,E) TLP2309(TPL,E) TLP2355(TPL,E TLP2358(E) TLP5214GR TLP521-4XGB TLP621XSM 5962-8876801PA IS281-4GB IS2805-4 IS181GR ICPL2630 ICPL2531 ICPL2601 ICPL2530 59628876801PC TLP2301 TLP2301(E(T TLP2362(TPR,E TLP754(F)